

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

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1. (original) A magnetic head comprising:
a substrate;
a read head being fabricated upon said substrate;
a P1 pole being fabricated upon said read head;
a write gap layer being fabricated upon said P1 pole;
a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole tip includes a first portion being comprised of a seed layer material and a second portion being comprised of electroplated material, and wherein said P2 pole tip has a width dimension W that is formed in part from a thickness of said seed layer material portion and in part from a thickness of said electroplated material portion.

2. (original) A magnetic head as described in claim 1 wherein said first portion of said P2 pole tip that is comprised of said seed layer material forms a sidewall of said P2 pole tip.

3. (original) A magnetic head as described in claim 1 wherein said seed layer material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

4. (original) A magnetic head as described in claim 3 wherein said seed layer material thickness is approximately 250 Å and said electroplated material thickness is approximately 1500 Å.

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5. (original) A magnetic head as described in claim 3 wherein said seed layer material is comprised of NiFe and said electroplated material is comprised of NiFe.

6. (original) A hard disk drive comprising:
at least one hard disk being fabricated for rotary motion upon a disk drive;
at least one magnetic head adapted to fly over said hard disk for writing data on said hard disk, said magnetic head including:
a substrate;
a read head being fabricated upon said substrate;
a P1 pole being fabricated upon said read head;
a write gap layer being fabricated upon said P1 pole;
a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole tip includes a first portion being comprised of a seed layer material and a second portion being comprised of electroplated material, and wherein said P2 pole tip has a width dimension W that is formed in part from a thickness of said seed layer material portion and in part from a thickness of said electroplated material portion.

7. (original) A hard disk drive as described in claim 6 wherein said first portion of said P2 pole tip that is comprised of said seed layer material forms a sidewall of said P2 pole tip.

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1 8. (original) A hard disk drive as described in claim 6 wherein said seed layer material is
2 formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated
3 material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

1 9. (original) A hard disk drive as described in claim 8 wherein said seed layer material
2 thickness is approximately 250 Å and said electroplated material thickness is approximately
3 1500 Å.

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1 10. (original) A hard disk drive as described in claim 8 wherein said seed layer material is
2 comprised of NiFe and said electroplated material is comprised of NiFe.

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A2

1 19. (new) A magnetic head comprising:
2 a substrate;
3 a read head being fabricated upon said substrate;
4 a P1 pole being fabricated upon said read head;
5 a write gap layer being fabricated upon said P1 pole;
6 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole
7 tip includes a base surface that is disposed upon said write gap layer and a side wall surface that
8 is disposed generally perpendicularly to said base surface, and wherein said base surface and said
9 side wall surface are comprised of a P2 pole tip seed layer material.

1 20. (new) A magnetic head as described in claim 19 wherein said base surface defines a
2 width W of said P2 pole tip and said sidewall defines a thickness t of said P2 pole tip.

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1 21. (new) A magnetic head as described in claim 20, wherein said P2 pole tip further
2 includes an electroplated material portion, and wherein said electroplated material portion is
3 formed in part upon said sidewall surface seed layer material.

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1 22. (new) A magnetic head as described in claim 21 wherein said seed layer material is
2 formed with a thickness of approximately 50 Å to approximately 500 Å, and said electroplated
3 material is formed with a thickness of approximately 100 Å to approximately 5000 Å.

1 23. (new) A magnetic head as described in claim 21 wherein said seed layer material
2 thickness is approximately 250 Å and said electroplated material thickness is approximately
3 1500 Å.

1 24. (new) A magnetic head as described in claim 21 wherein said seed layer material is
2 comprised of NiFe and said electroplated material is comprised of NiFe.